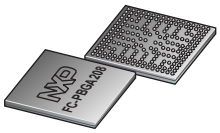
SOT2175-1

FC-PBGA208, flip chip - plastic ball grid array, 208 terminals, 0.3 mm pitch, 9 mm x 9 mm x 0.896 mm body

26 March 2026 **Package information**



1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FC-PBGA208
Package style descriptive code	FC-PBGA (flip chip - plastic ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	23-01-2025
Manufacturer package code	98ASA01895D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	8.85	9	9.15	mm
package width	8.85	9	9.15	mm
seated height	0.792	0.896	1	mm
nominal pitch	-	0.3	-	mm
actual quantity of termination	-	208	-	

2 Package outline

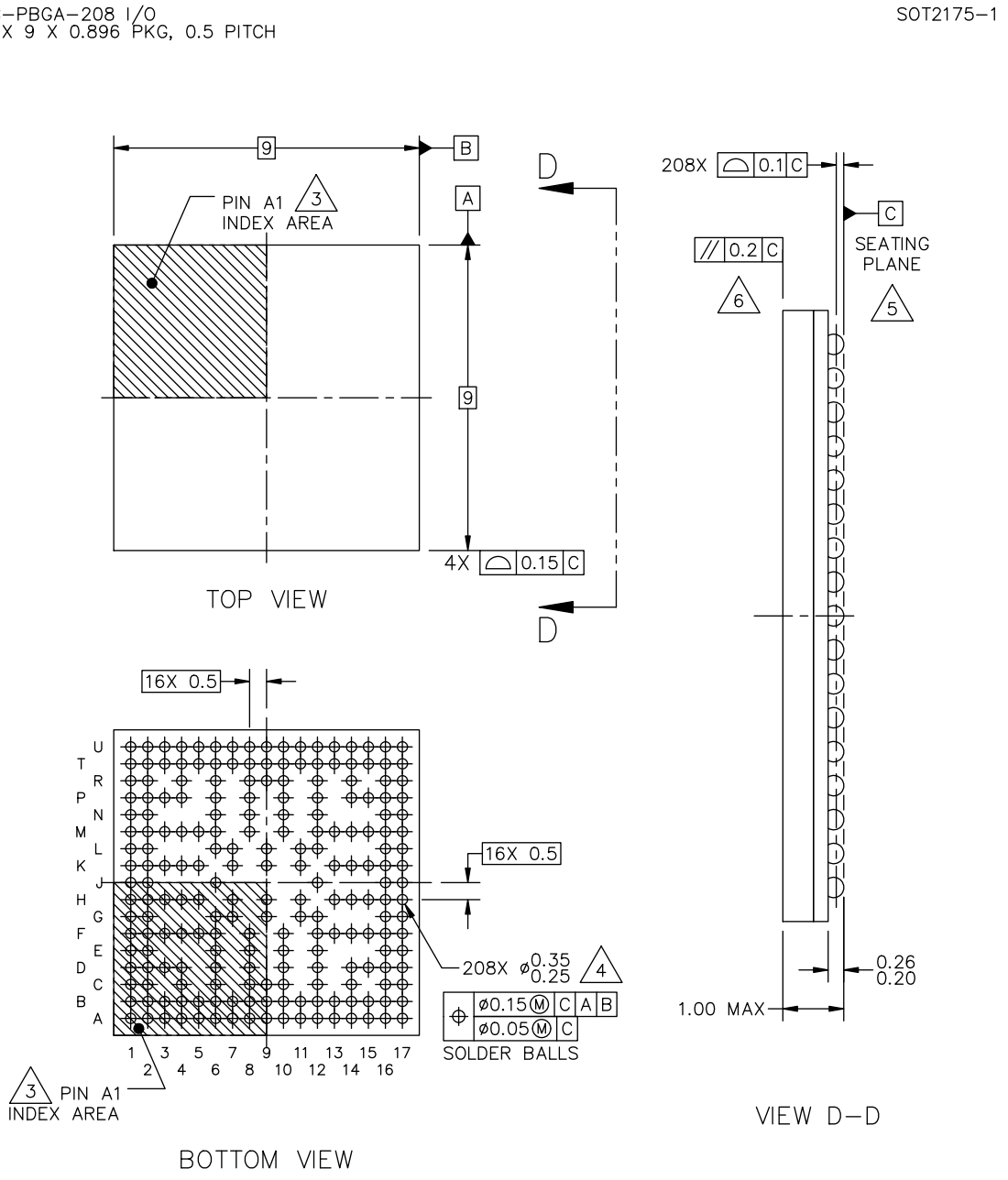


Figure 1. Package outline FC-PBGA208 (SOT2175-1)

3 Soldering

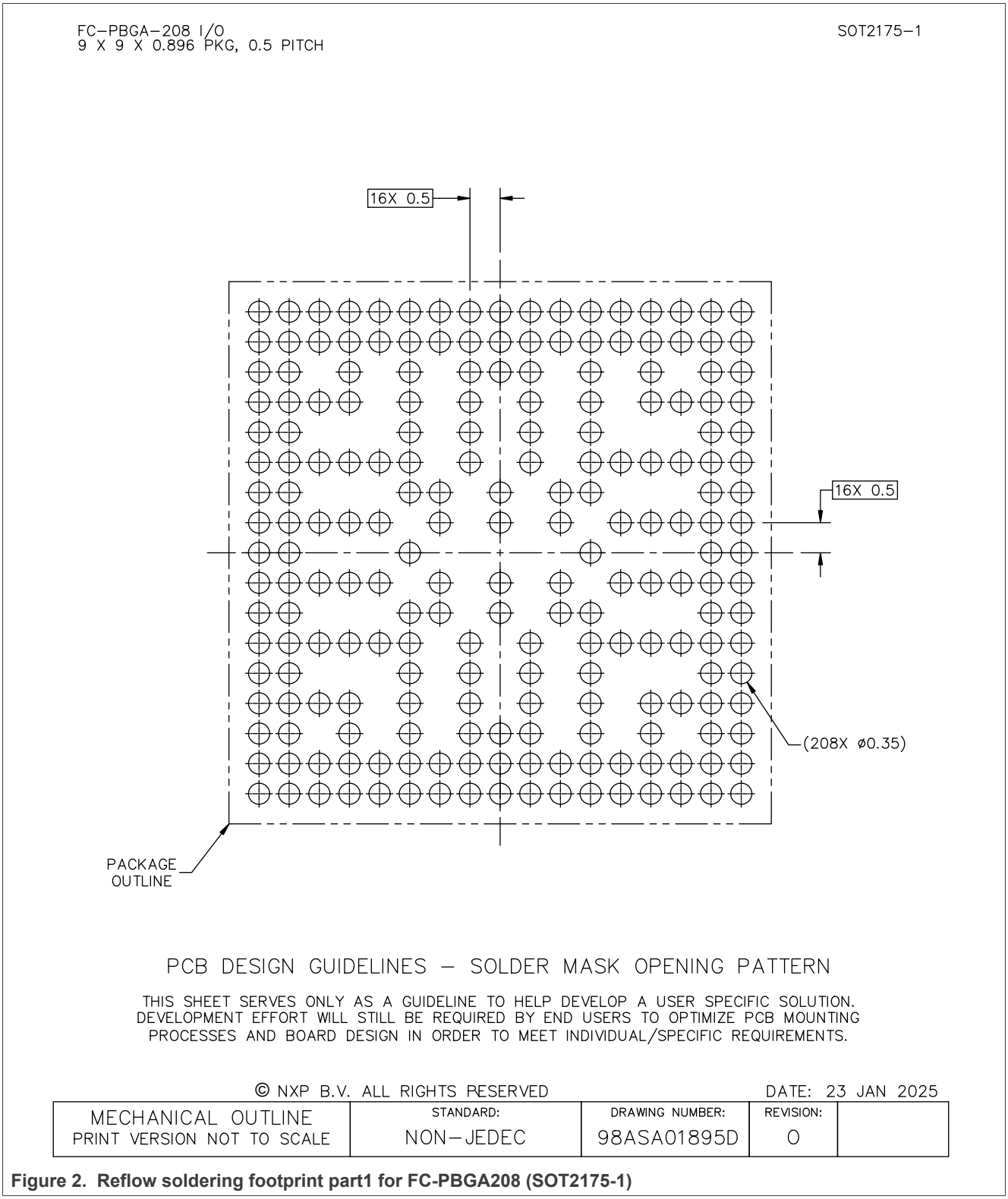


Figure 2. Reflow soldering footprint part1 for FC-PBGA208 (SOT2175-1)

FC-PBGA208, flip chip - plastic ball grid array, 208 terminals, 0.3 mm pitch, 9 mm x 9 mm x 0.896 mm body

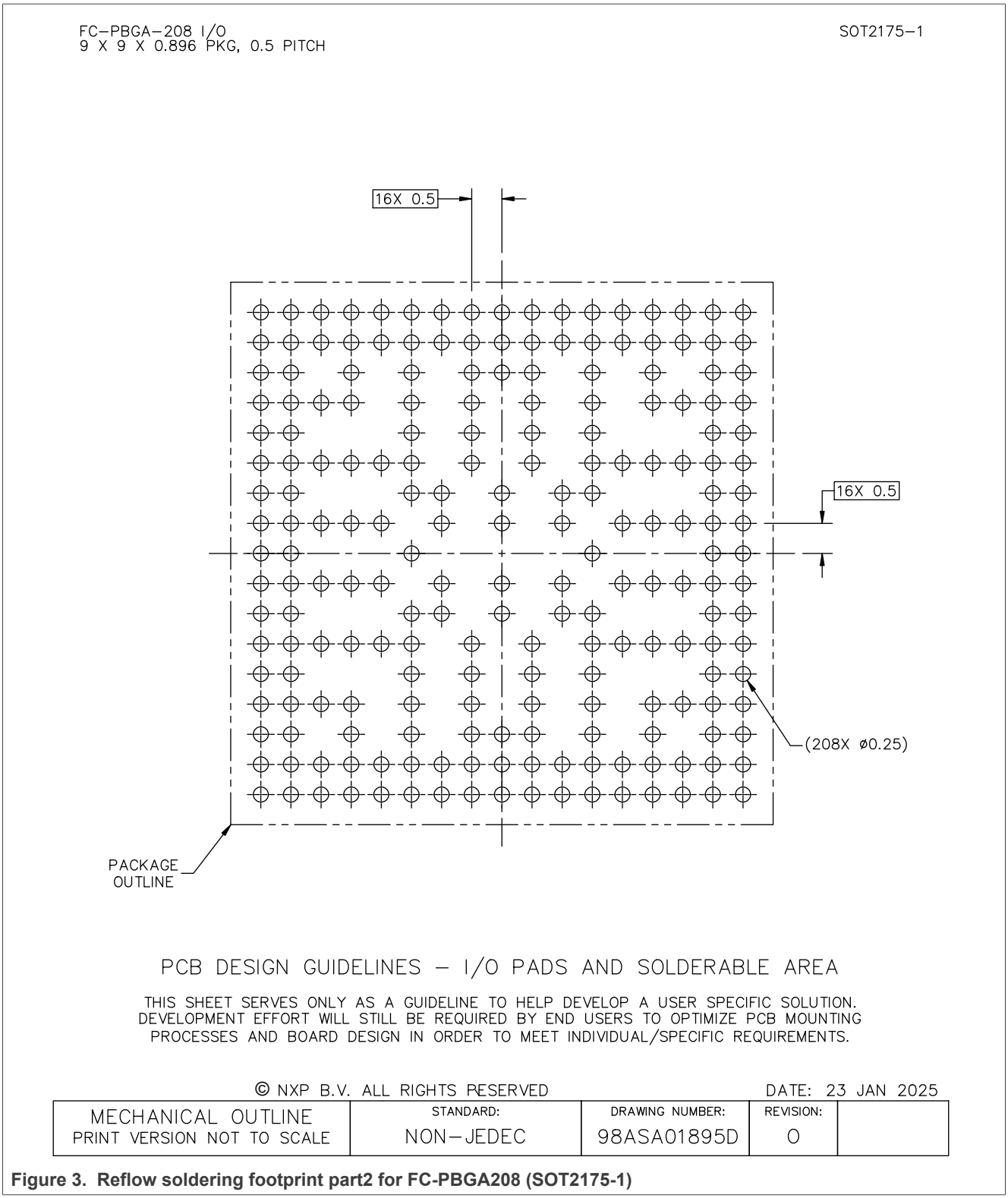


Figure 3. Reflow soldering footprint part2 for FC-PBGA208 (SOT2175-1)

FC-PBGA208, flip chip - plastic ball grid array, 208 terminals, 0.3 mm pitch, 9 mm x 9 mm x 0.896 mm body

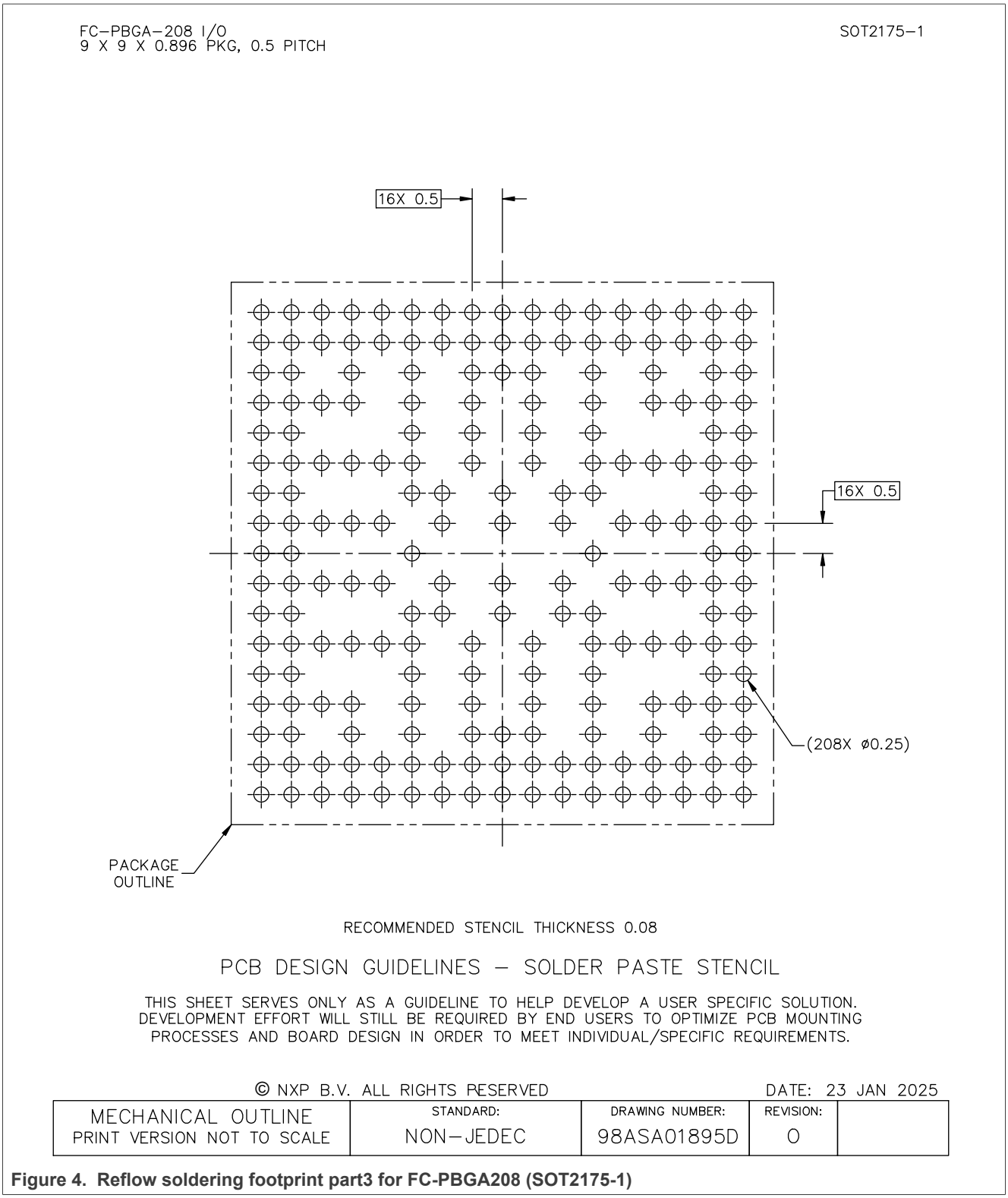


Figure 4. Reflow soldering footprint part3 for FC-PBGA208 (SOT2175-1)

FC-PBGA208, flip chip - plastic ball grid array, 208 terminals, 0.3 mm pitch, 9 mm x 9 mm x 0.896 mm body

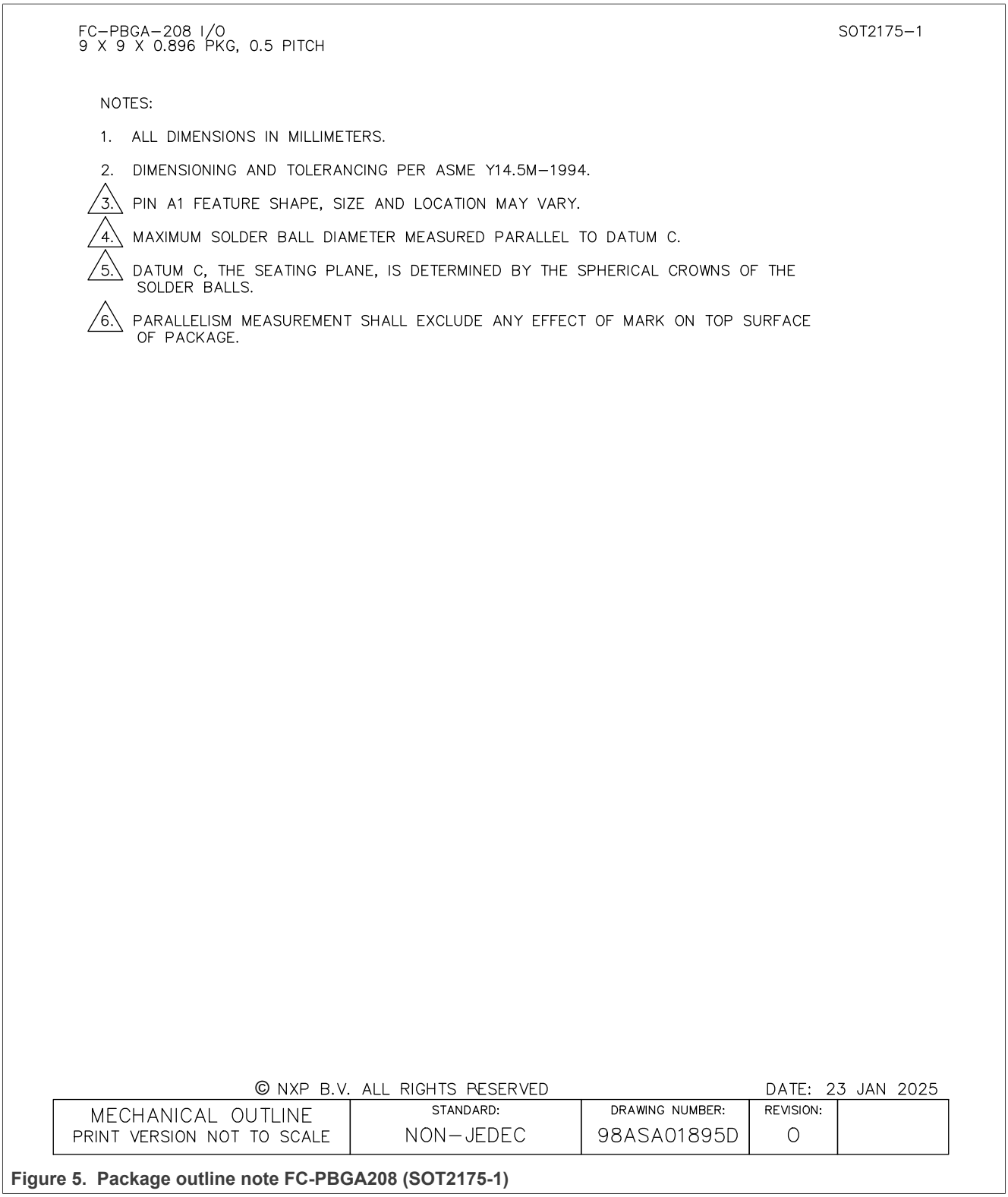


Figure 5. Package outline note FC-PBGA208 (SOT2175-1)

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Contents